

## Special Issue

# Nanoscale Assembly and Integration for Applications

### Message from the Guest Editor

Nanoscale materials and applications now occupy a central role in research and commercial products ranging from electronics and biotechnology to automobiles and aircrafts. The field continues to grow at a rapid pace fueled by a global effort—involving governments, academia and industry—that has been enabled by advances in nanofabrication, which underpins the application of nanoscale materials. A key challenge in nanofabrication is the control and integration of structures as desired in order to deliver novel materials and applications at the nanoscale (~1 to 100 nm). By controllably assembling nanomaterials, their excellent properties can be harnessed for enhanced performance and emerging applications in computing, information technology, energy, sensing, health and security.

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### Guest Editor

Prof. Chris Papadopoulos

Department of Electrical and Computer Engineering, University of Victoria, Victoria, BC, Canada

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### Deadline for manuscript submissions

closed (25 March 2022)



## Applied Sciences

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### Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal *Applied Sciences* has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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### Editor-in-Chief

Prof. Dr. Giulio Nicola Cerullo  
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